



Applied Micro Circuits Corporation

ARM-based Scale-out Servers

OCP-J Meet up Event June 23, 2016

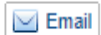
Applied Micro at the OCP – Jan 16 2013

AppliedMicro Contributes First ARM-Based Microserver Specification to Open Compute Project

World's First ARM® 64-bit Server Board Based on New Specification Debuts at Open Compute Summit



MARKETWIRE Press Release: AppliedMicro – Wed, Jan 16, 2013 1:00 PM EST



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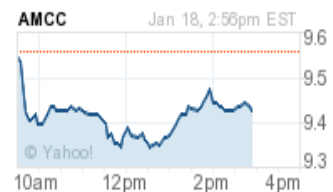
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RELATED QUOTES

Symbol	Price	Change
AMCC	9.44	-0.12



SANTA CLARA, CA--(Marketwire - Jan 16, 2013) - Open Compute Summit - Applied Micro Circuits Corporation (NASDAQ : AMCC) today announced that it has signed its contribution license with the Open Compute Project (OCP) Foundation, developing the first micro server board design specification based on the ARMv8 architecture. The design will leverage the AppliedMicro® X-Gene™ platform, the industry's first ARM 64-bit Server on a Chip™ solution.









As the first ARMv8 contribution to the OCP Motherboard Working Group, the new specification contributed by AppliedMicro will be the foundation for purpose-built cloud and

enterprise server deployments specifically focusing on increased density and field serviceability resulting in a lower total cost of ownership (TCO).

"The X-Gene platform is designed to deliver unprecedented low power, high performance and integration, with the goal of changing the way servers are designed for cloud and enterprise applications," said Dr. Paramesh Gopi, president and CEO of AppliedMicro. "This purpose-built server on a chip and open source software deliver the cost efficiency, power and performance needed to serve evolving data center workloads. And, with X-Gene silicon slated to sample to key customers this quarter, an ARM 64-bit server motherboard design has the potential to reach the data center by the end of this year."



Unique Complement of Products Leverages World-class Engineering Capability, Extensive IP Portfolio, and Top Tier Customer Base

Segment	Module Name	Module Description	Sample Customers / System Partners
Compute	 X-Gene1	<ul style="list-style-type: none"> X-Gene based X-C1 Server Development Platform 	<ul style="list-style-type: none"> Tier 1 Global Internet Company Tier 1 e-Commerce Company Tier 1 Enterprise Software Company Tier 1 Global IT Company Tier 1 Cloud Computing Company Tier 1 Semiconductor Company Tier 1 Computer Technology Company Tier 1 China Internet Company Tier 1 Operating System Company
	 X-Gene2	<ul style="list-style-type: none"> X-Gene 2: 28nm of X-Gene that includes RDMA on-chip 	
	 X-Gene3	<ul style="list-style-type: none"> X-Gene 3: to be fabricated using advanced FinFET process technology; samples 2H'2016 	
Embedded	 HeliX1	<ul style="list-style-type: none"> Embedded processors handle system maintenance and remote management functionality Network, Security, Memory Acceleration Card 	<ul style="list-style-type: none"> Tier 1 Enterprise Storage Company Tier 1 Telecommunications Company Tier 1 Surveillance Appliance Company
	 HeliX2	<ul style="list-style-type: none"> HeliX2: industry's first fanless high-performance 28nm embedded ARM 64-bit SoC COM Express Module with 10G NIC 	
Connectivity	 Service Provider Connectivity Solutions	<ul style="list-style-type: none"> High-density, low-power 10 / 100 / 400G optical transport network (OTN) framer/PHY SoCs designed for service providers and data center networks High performance analog / mixed-signal PHY devices for 10 / 40 / 100 / 400G modules 	
	 Data Center Connectivity Solutions	<ul style="list-style-type: none"> Supports 100 / 400 Gbps of connectivity with multi-protocol features and high density Targets needs of high-bandwidth applications in public cloud, private cloud and enterprise data centers 	

ARM Platforms Powered by X-Gene

wistron



MITAC



kontron

Cirrascale

E4
COMPUTER
ENGINEERING



EuroTech



Hewlett Packard
Enterprise

uniserver

Data Center



HP ProLiant m400



Tier 1 China
Hyperscale end users

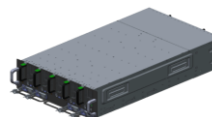


Gigabyte R120-P30 & MP30



ODM Platforms

Storage



Wistron X5 OCP
Platform



Tier 1 Server Storage
Platforms

Networking



Tier1 Datacenter Switch
Platforms



Kontron SYMCLOUD T4010

High-Performance Computing



E4 ARKA RK003



Cirrascale RM2916



Eurotech Aurora
"Hive"

X-Gene Software Ecosystem



Operating Systems



Hypervisors & Java



BIOS & Tools

Wistron X5 OCP Multi-Server

Platform Features

Flexible SKUs to support different application

Easy swap in Computing or Storage based on customer requests

Front 10G (Storage) or 40G/100G(Computing) Networking access

3 +1 Redundant PSU design

Front to back cooling

Configuration Features

Processor Support

Up to 160 ARM cores per 5U:
Up to 20 x AppliedMicro X-Gene 1 with 8 cores @ 2.4GHz
ARMv8 64-bit cores (8)

I/O

Networking:

- 10GbE for each Node for a total of 170Gbps
- Up to 25GbE to each Nodes

Memory:

- Up to 640GB DDR3 memory

Storage:

- Up to 400TB of 3.5" HDD
- Up to 25.6TB of 2.5" SSD

Chassis

5U x W435 x D800 mm
Hot swap fans
Front to back cooling

Power

N+1 redundant up to 4800W AC Hot Swap Power Supplies
80 PLUS® silver or better efficiency
Intelligent Power Management

Operating Temp.

35 C

Support

Managed Life Support (5-7 years)

Availability

PoC available for trial now





APM's 3rd Generation Server Solution

X-Gene[®] 3 Overview

Processor Subsystem

- 32 ARM[™] v8 64-bit CPU cores at up to 3 GHz

Memory

- Eight DDR4-2667 channels – 1TB per socket

Connectivity

- 42 lanes of PCIe Gen 3

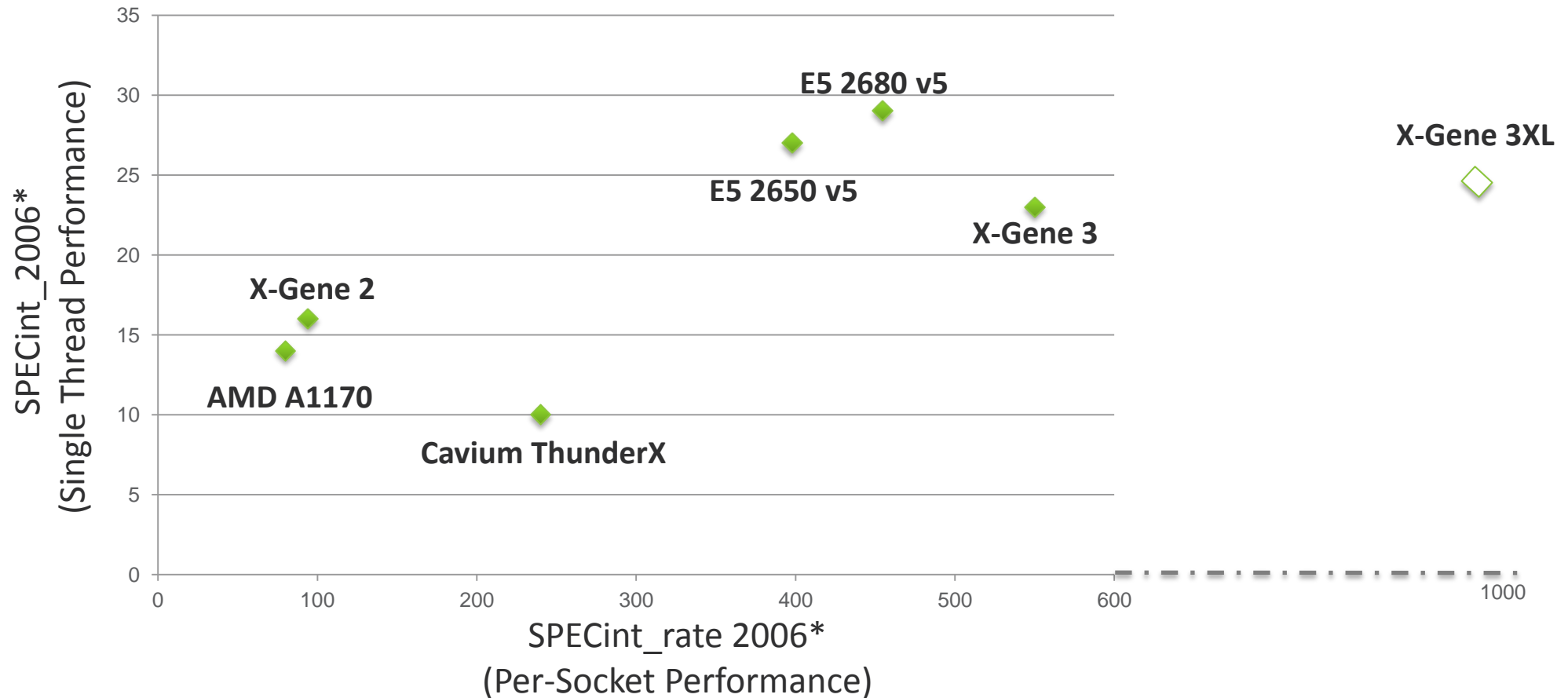
Performance

- 6X performance versus current generation
- Intel Xeon[®] Skylake E5 class socket performance

Sampling 2H'2016

Server Processor: Competitive Landscape

* SPECint and SPECint_rate peak, using GCC -O3



X-Gene 3 and 3XL target the compute performance of mainstream E5 sockets

